



CSP/MICRO BGA Test & Burn-in Socket For Devices From 14 - 27mm Sq.

FEATURES:

- For Test & Burn-In of CSP, MicroBGA, DSP, LGA, SRAM, DRAM and Flash Devices. Consult Factory for QFP applications.
- Any pitch device on 0.40mm or larger.
- Pressure mounting, no soldering required.
- 4 Point crown insures "scrub" on solder oxides.
- Signal path during test only .077" (1.92mm)
- Accommodates any package up to 27mm².
- Small overall socket size/profile allows maximum number of sockets per BIB and BIB's per oven, while being operator friendly.
- **SPECIFICATIONS:**
- Molded socket components are UL94V-0 PEEK and/or Ultem.
- 1dB Bandwidth at 1Ghz (0.80mm pitch) (large probe).
- Estimated Contact Life: =500,000 cycles.
- Compression spring probes are heat treated Beryllium Copper Alloy with 30u" min. [.75um] Gold per Mil-G-45204 over 30u" min.[.75um] Nickel per SAE-AMS-QQ-N-290.
- Contact Force = 16g per contact on 0.40mm pitch.
= 25g per contact on 0.50 - 0.75mm & 0.80mm pitch or larger
- Operating Temperature = -55°C (min.) to 150°C (max.); -67°F (min.) to 302°F (max.).
- All Hardware is Stainless Steel.
- Typical Burn-in Temperature = 150°C Max.

MOUNTING CONSIDERATIONS:

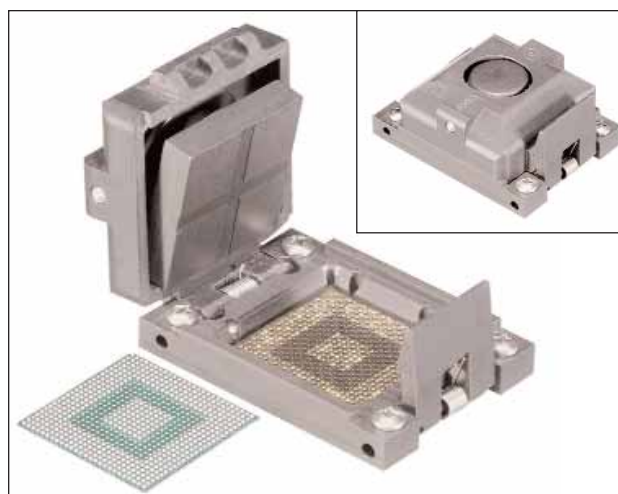
- Socket is mounted with (4) four #4-40 screws to either a plastic shipping plate (to be removed at time of socket mounting or PCB) or a tapped insulated backing plate to be used on underside of PCB for high pin count applications.
- Sockets must be handled with care when mounting or removing sockets to/from PCB.
- Test board PCB dia. :
= .025" (0.635mm) (large probe = 0.80mm pitch or larger)
= .015" (0.381mm) (small probe = 0.50 - 0.75mm pitch)
= .012" (0.300mm) (small probe = 0.40mm pitch)

ALL DIMENSIONS: INCHES [MILLIMETERS]

All tolerances ± .005 [.13]
unless otherwise specified

SEE CSP DATASHEETS:
23017 FOR UP TO 13MM
23019 FOR UP TO 40MM
23020 FOR UP TO 55MM

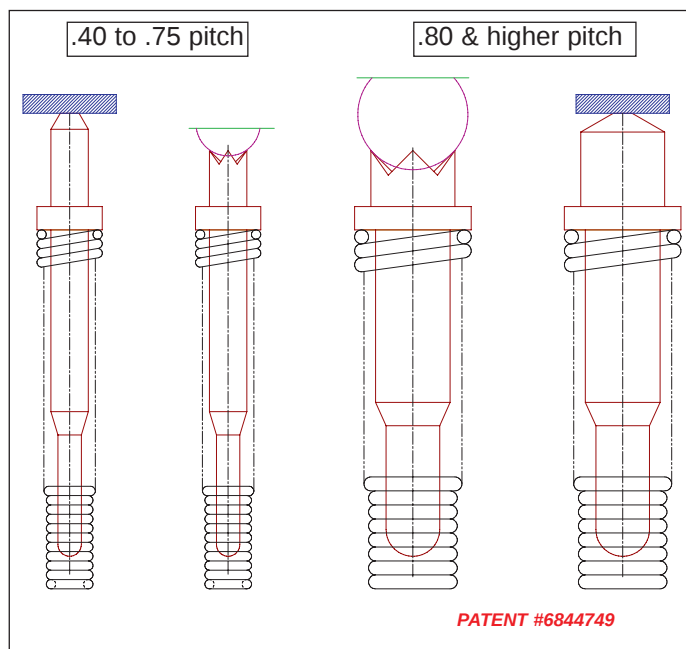
SPRING
PROBES



Note: Aries specializes in custom design and production. In addition to the standard products shown on this page, special materials, platings, sizes, and configurations can be furnished, depending on quantities. Aries reserves the right to change product specifications without notice.

ORDERING INFORMATION

CONSULT FACTORY



PATENT #6844749



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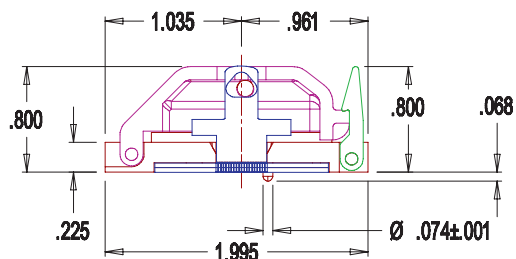
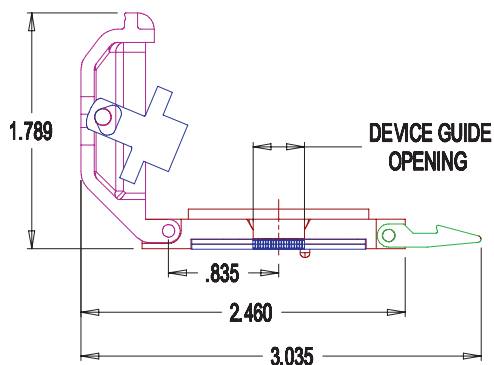


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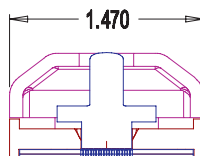
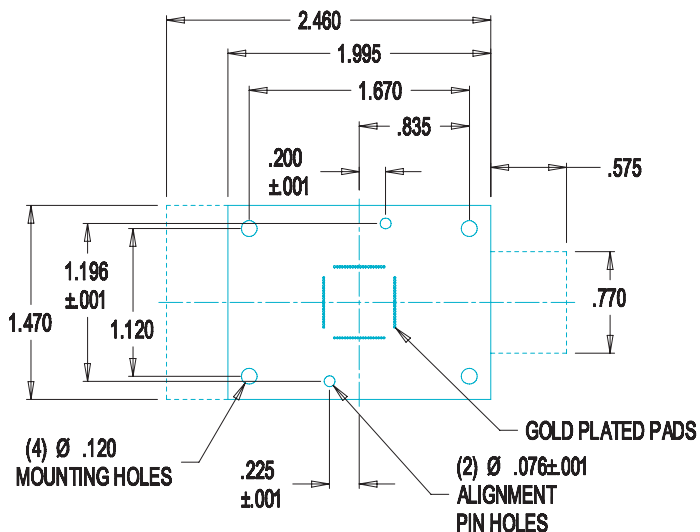


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REFERENCE ONLY DRAWINGS



FOOTPRINT TOP VIEW



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